

ABSTRACT

The invention relates to a heat sink component (40) made of a thermally conductive material and intended to thermally connect an optoelectronics sensor (10) to a rigid cradle (30) cooled by external cooling means;

the optoelectronics sensor (10) being mounted on a printed circuit (20); the cradle having at least one fixing boss (32) and an opening (31) intended to house the optoelectronics sensor (10);

said heat sink component (40) comprising:

- a base (41) intended to be placed in thermal contact with at least one fixing boss (32) of the cradle;
- a protuberance (42) intended to be placed in thermal contact with a lower face of the optoelectronics sensor (10) through a hole passing through the printed circuit (20).

Figure for the abstract: Fig. 1b